

ABSTRACT OF THE DISCLOSURE

A routing element for use with a multi-chip module. The routing element includes a substrate that carries conductive traces that provide either additional electrical paths or shorter electrical paths than those provided by a multi-chip module substrate. The conductive traces may be carried upon a single surface of the routing element substrate, internally by the routing element substrate, or include externally and internally carried portions. The routing element also includes a contact pad positioned at each end of each conductive trace thereof to facilitate electrical connection of each conductive trace to a corresponding terminal of the substrate or to a corresponding bond pad of a semiconductor device of the multi-chip module. Multi-chip modules are also disclosed, as are methods for designing the routing element and methods in which the routing element is used.

N: 2269 4813 pat app.wpd 8 29 01